

# Lab 1 Part2: MOSFET Characteristics

**Note:** Comments are written only in part (A) to avoid redundancy.

## A) Using ADT

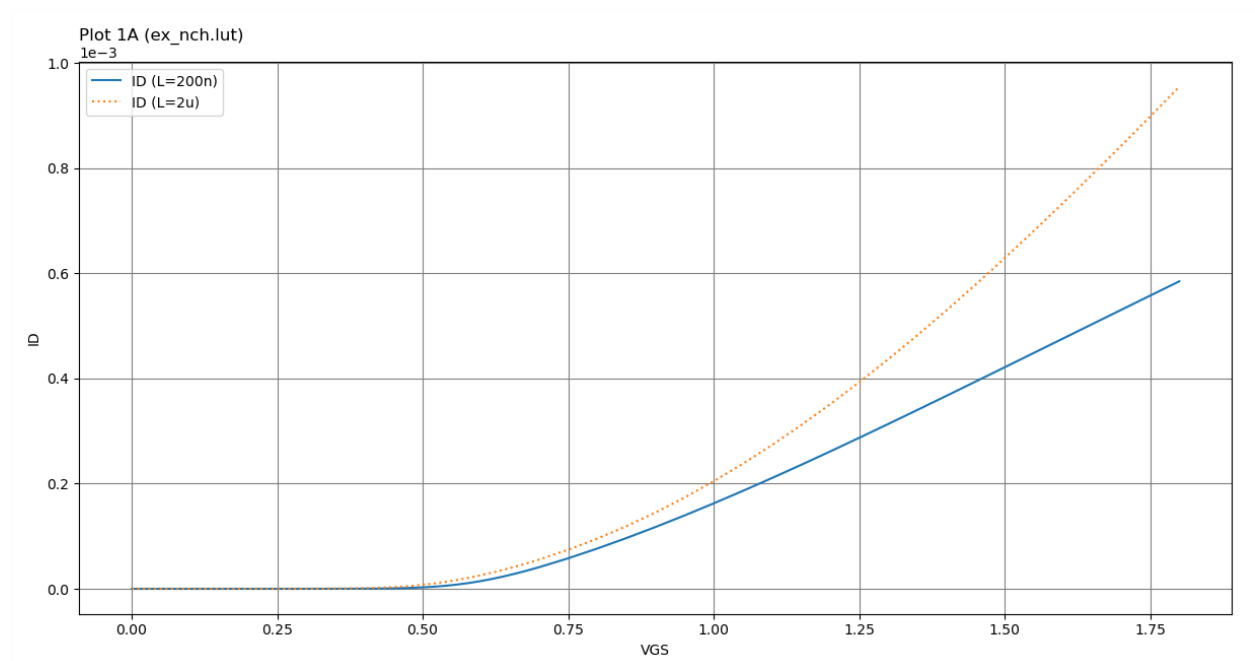
### ID vs VGS

#### Desired Sizes

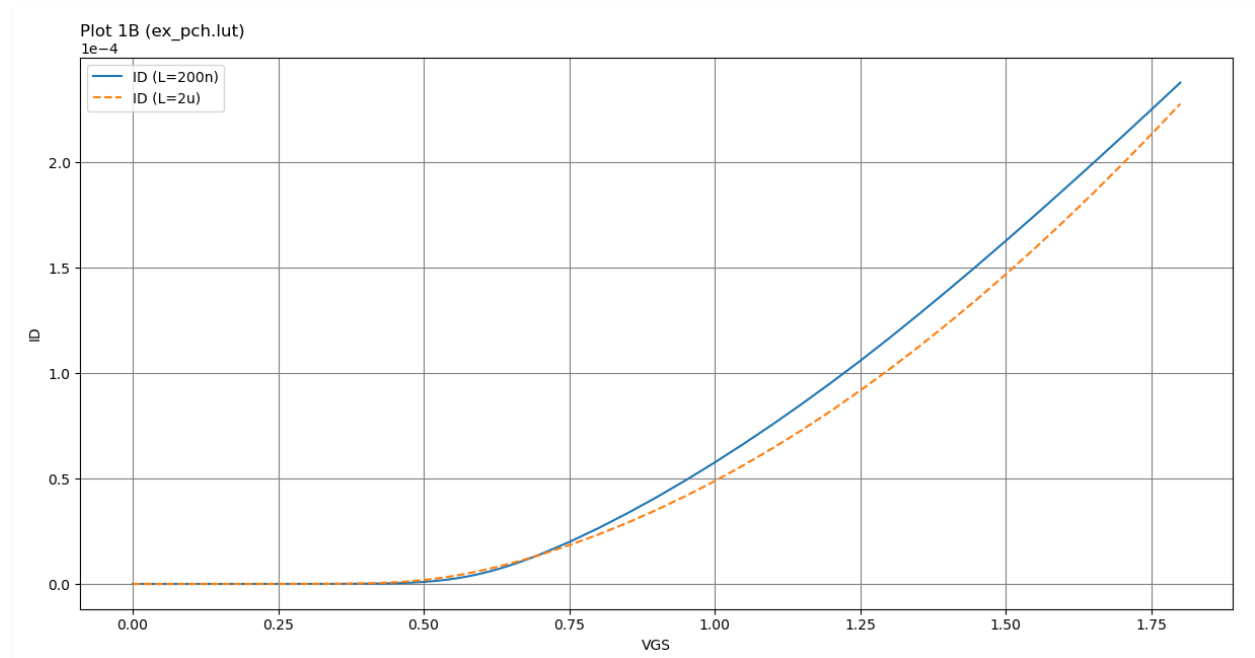
Y-Expr:	<input type="text"/>	?
L:	<input type="text" value="200n"/>	?
VGS	<input type="text" value="1.8"/>	?
VDS:	<input type="text" value="1.8"/>	?
VSB:	<input type="text" value="0"/>	?
W	<input type="text" value="1μ"/>	?

Y-Expr:	<input type="text"/>
L:	<input type="text" value="2μ"/>
VGS	<input type="text" value="1.8"/>
VDS:	<input type="text" value="1.8"/>
VSB:	<input type="text" value="0"/>
W	<input type="text" value="10μ"/>

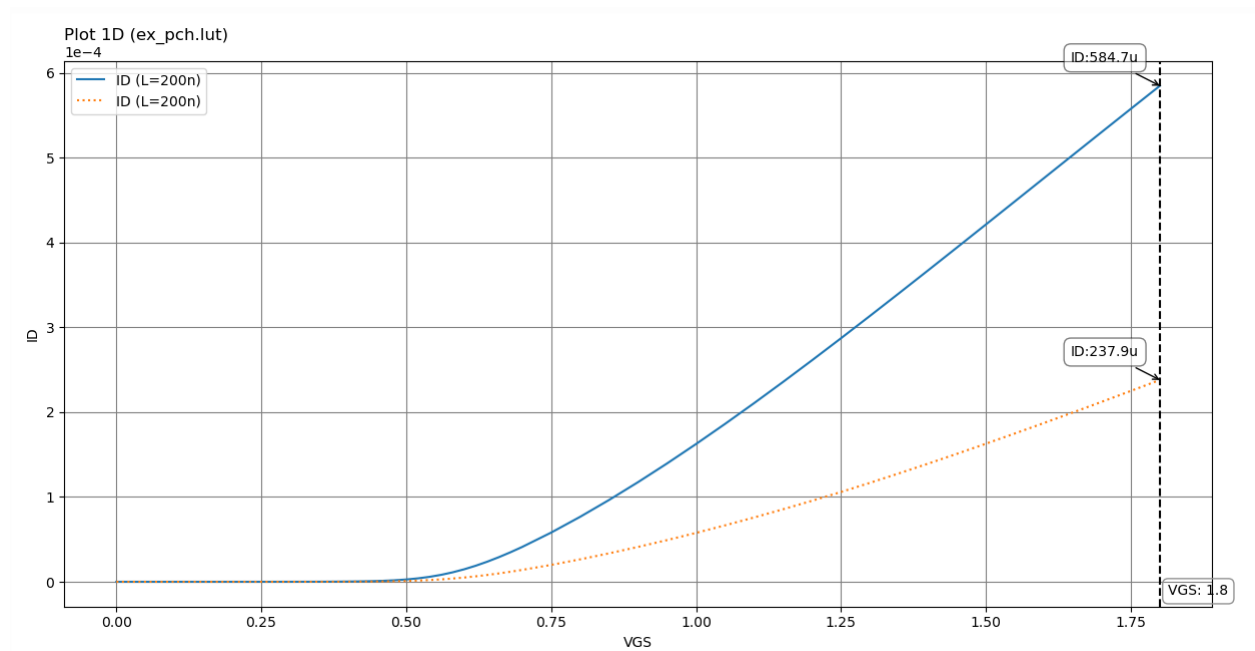
#### NMOS (Short Channel vs Long Channel)



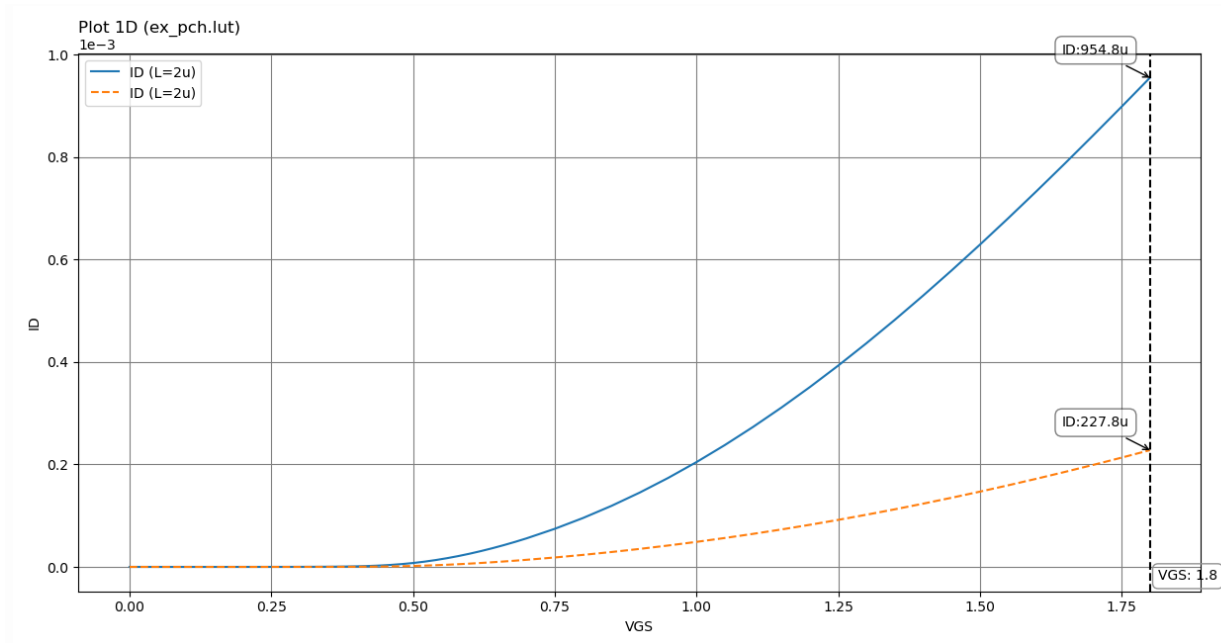
## PMOS (Short Channel vs Long Channel)



## NMOS vs PMOS (Short Channel)



## NMOS vs PMOS (Long Channel)



### Comments on Short Channel vs Long Channel

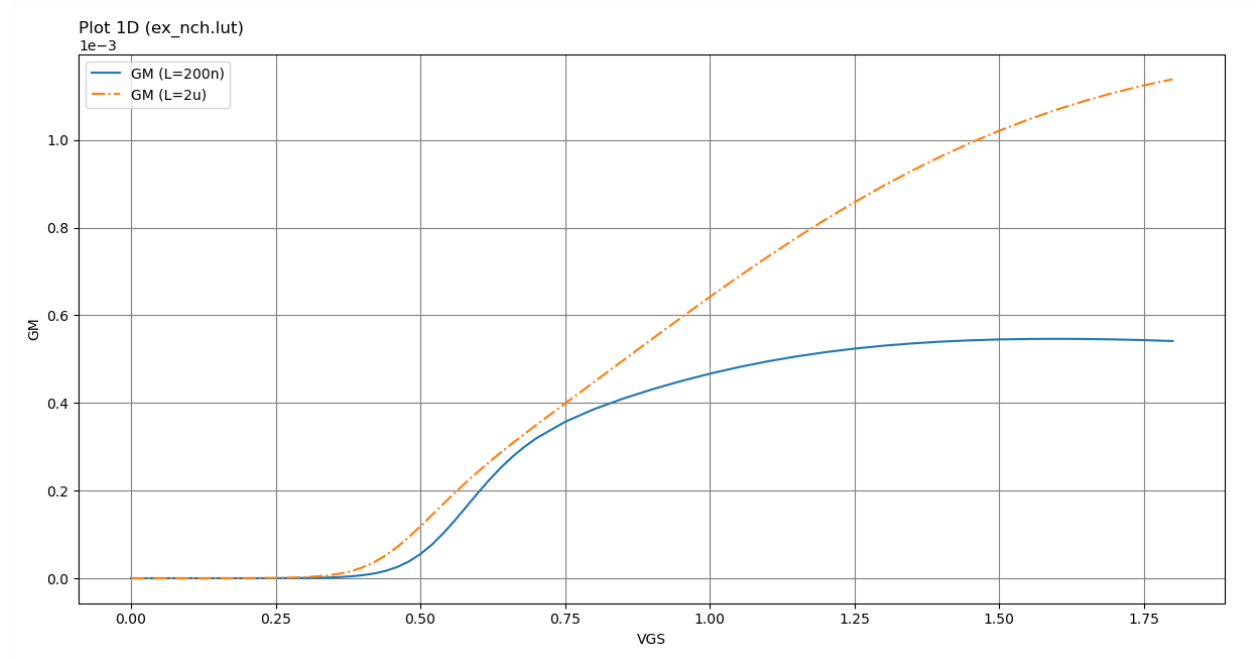
- The short channel MOSFET has a lower current than long channel MOSFET due to velocity saturation. In short channel, velocity saturation occurs before pinch-off when  $V_{DSsat} > V_{ov}$ . This means that the carriers reach their maximum velocity in the channel before the channel is fully depleted near the drain.
- The drain current ( $I_D$ ) varies quadratically with  $V_{GS}$  in both channels until  $V_{GS} = V_{th} + V_{DSsat}$ . After this point, the drain current ( $I_D$ ) varies **linearly** with  $V_{GS}$  in **short** channel ( $I_D = C_{ox} \cdot W \cdot v_{sat} \cdot (V_{ov} - V_{DSsat}/2) \cdot (1 + \lambda \cdot V_{DS})$ ). The drain current ( $I_D$ ) continues to vary **quadratically** with  $V_{GS}$  in **long** channel ( $I_D = (\mu_n C_{ox}/2) \cdot (W/L) \cdot (V_{ov})^2$ ).

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## Comments on NMOS vs PMOS

- NMOS has higher current than PMOS, because electrons have higher mobility than holes in silicon.
- Current ratio (NMOS/PMOS) at  $V_{GS} = V_{DD}$ :
  1. **Short Channel:**  $584.7/237.6 = 2.46$
  2. **Long Channel:**  $954.8/227.8 = 4.19$
- PMOS is less affected by short channel effects, because holes have lower mobility than electrons, which means that the carrier speed is usually smaller than  $v_{sat}$ .

## gm vs VGS (NMOS)

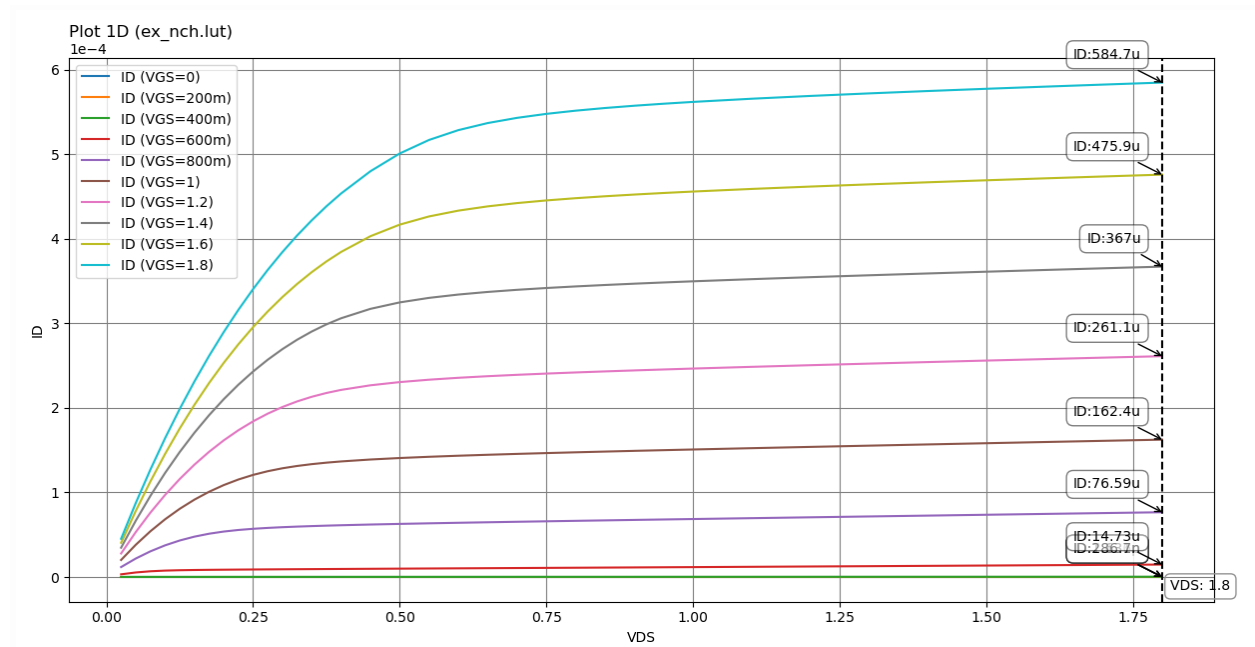


## Comments

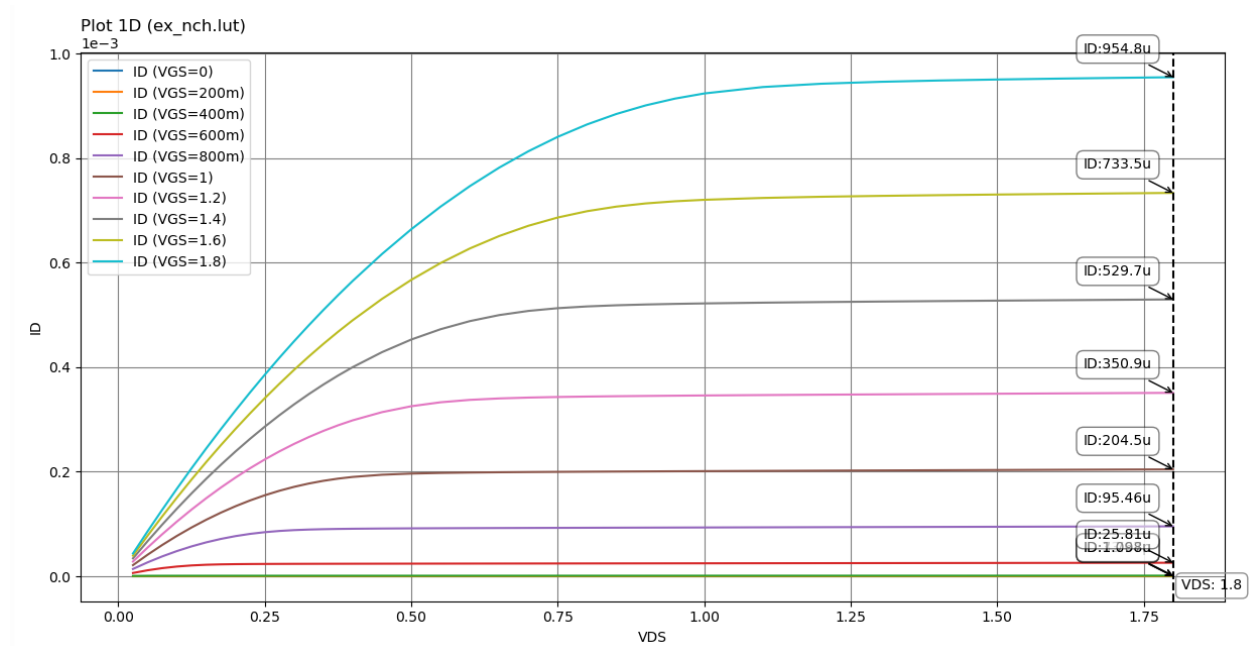
- $gm = \frac{\partial I_D}{\partial V_{GS}}$
- In long channel, the graph is linear as it is the derivative of a quadratic function.
- In short channel, the graph saturates as it is the derivative of a linear function.
- Due to mobility degradation,  $gm$  might decrease if  $V_{GS}$  is further increased than 1.8 (VDD).

## ID vs VDS (NMOS)

### Short Channel



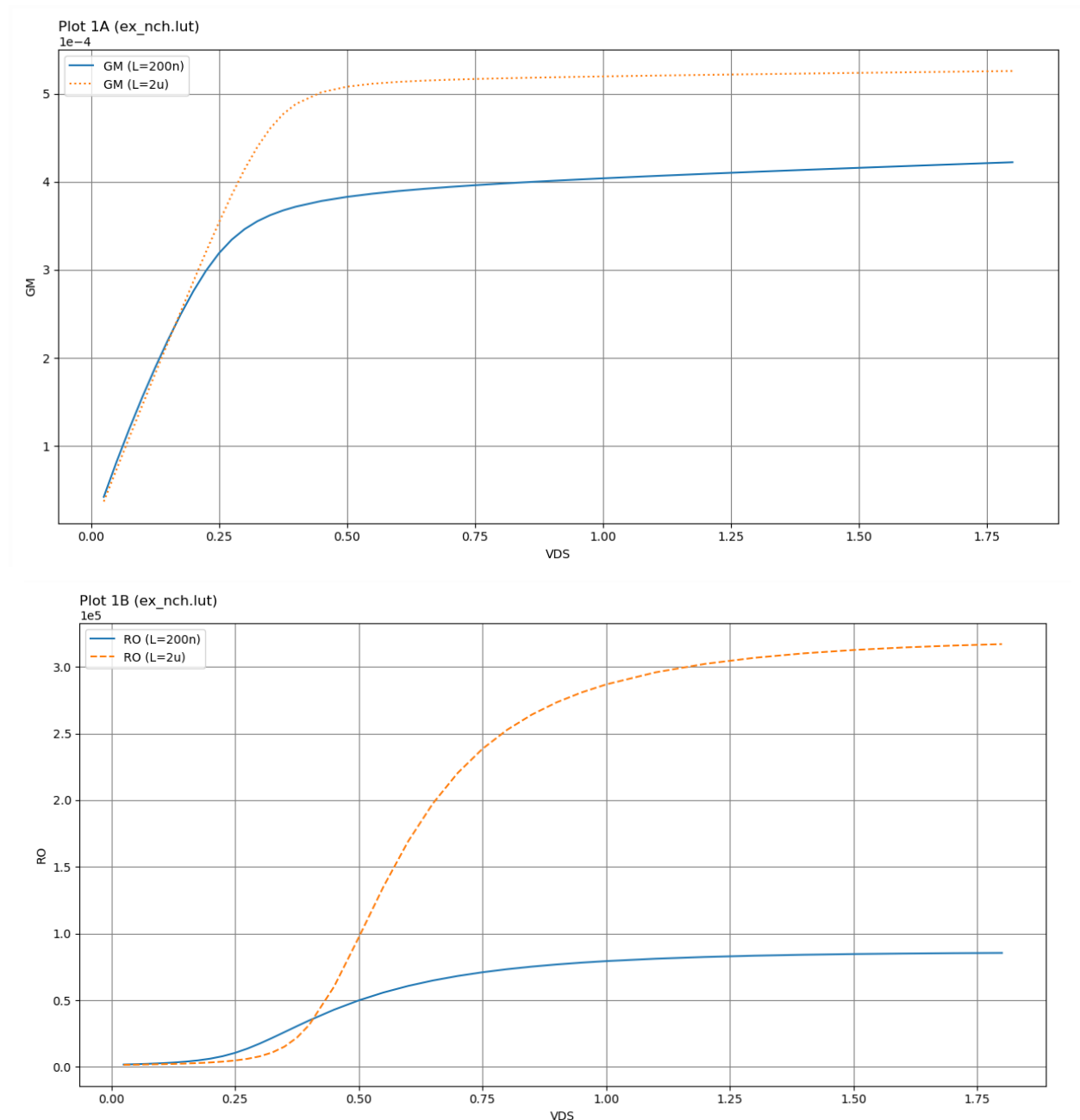
### Long Channel



## Comments

- Long channel has a higher current than short channel, as short channel is incredibly affected by velocity saturation as well as mobility degradation.
- Slope of short channel in saturation region is higher than long channel due to channel length modulation as well as drain-induced barrier lowering.

## gm and ro in Triode and Saturation (NMOS)



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## gm Comments

- In triode region (first part of curve where  $V_{DS} < V_{GS} - v_{th}$ ), the transconductance is given by the derivative of drain current with respect to  $V_{GS}$  [ $g_m = (\mu_n)(C_{ox})(W/L)(V_{DS} - V_{DS}^2/2)$ ]. In this region,  $V_{DS}$  has a small value so  $(V_{DS}^2/2)$  term can be neglected making a **linear** relation between  $g_m$  and  $V_{DS}$  in this region.
- $g_m$  saturates in saturation region, where  $V_{DS} > V_{GS} - v_{th}$ . The transconductance is given by this equation [ $g_m = (\mu_n)(C_{ox})(W/L)(V_{ov})$ ]. Therefore,  $g_m$  is independent on  $V_{DS}$  in this region.
- In analog amplifier applications, we want to operate in saturation region. In saturation region, we can obtain high values of  $g_m$  and  $r_o$ . Therefore, we can get a large gain from the circuit (intrinsic gain =  $g_m r_o$ ).

## ro Comments

- $r_o$  does **not** saturate just after the transistor enters saturation. This is due to dependence of Early voltage on  $V_{DS}$ ;  $V_A$  increases with  $V_{DS}$  and  $r_o = V_A/I_{DS}$ .
- $r_o$  **increases** if the transistor is biased more into saturation. In the beginning of saturation region, the curve has a big slope (small  $r_o$ ), while in deep saturation the slope is small (big  $r_o$ ) as slope =  $1/r_o$ .
- We should **not** operate at the edge of saturation. Despite having the maximum  $g_m$  at edge of saturation,  $r_o$  is small as well as signal swing is limited.
- In analog amplifier applications, we want to operate in saturation region. In saturation region, we can obtain high values of  $g_m$  and  $r_o$ . Therefore, we can get a large gain from the circuit (intrinsic gain =  $g_m r_o$ ).

## B) Using ADTSA

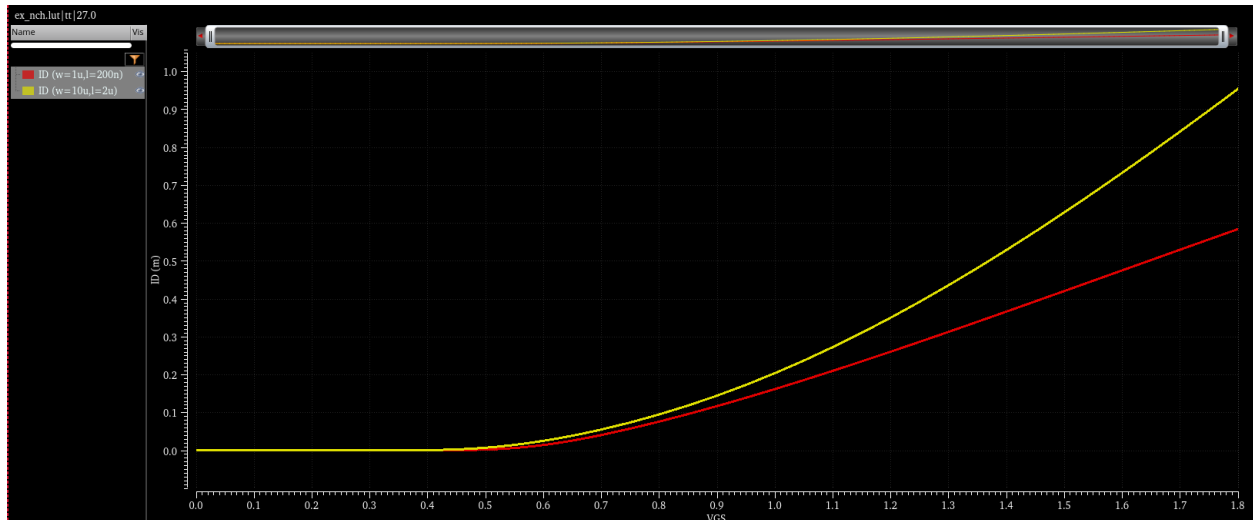
### ID vs VGS

#### Desired Sizing

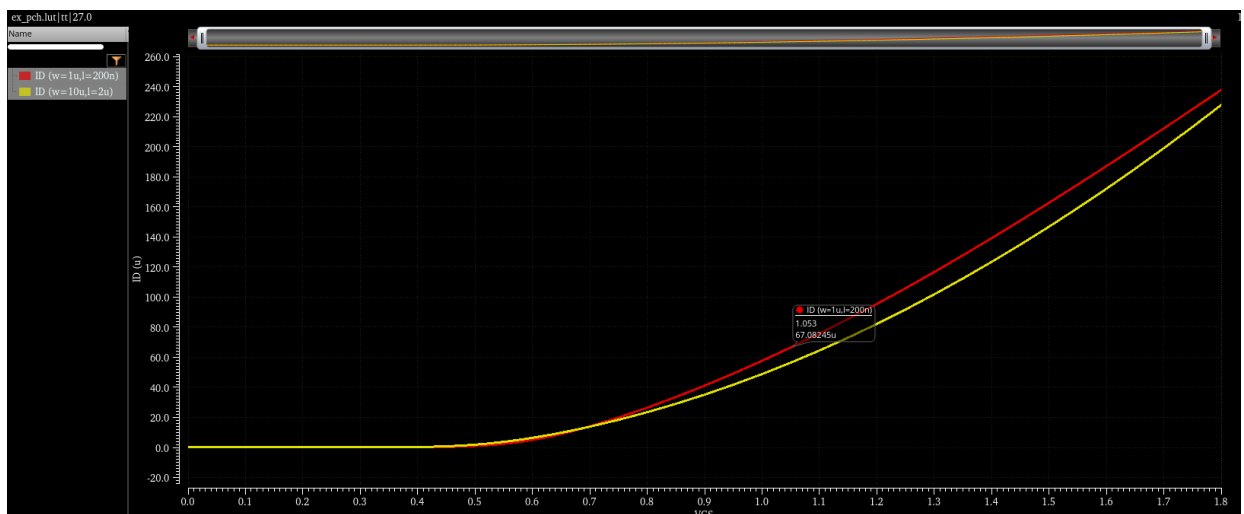
W	▼	1u
VGS	▼	
L	▼	200n
VDS	▼	1.8
VSB	▼	0

W	▼	10u
VGS	▼	
L	▼	2u
VDS	▼	1.8
VSB	▼	0

#### NMOS (Short Channel vs Long Channel)

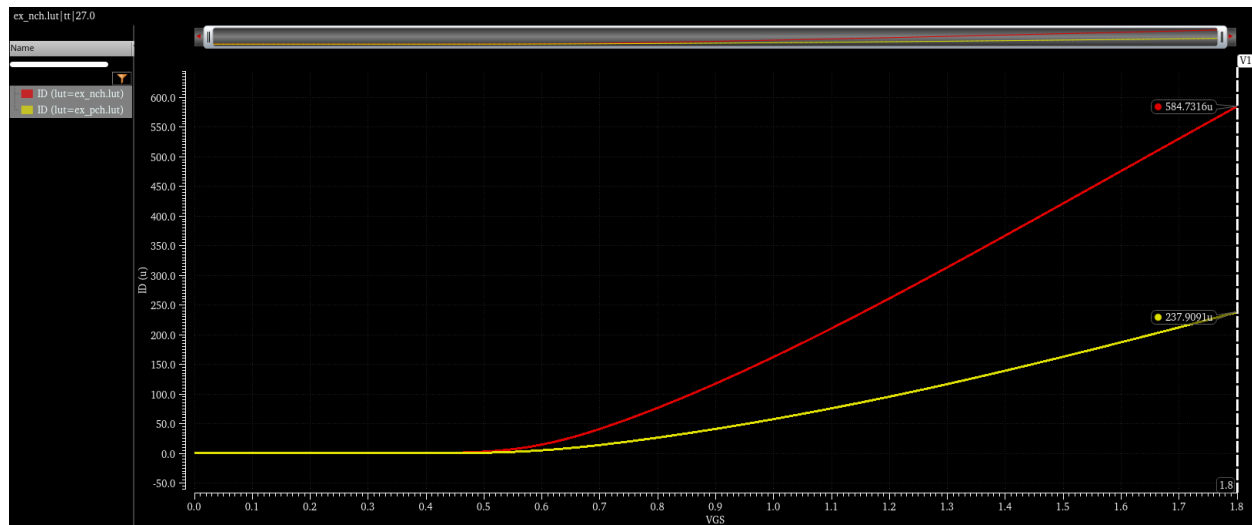


#### PMOS (Short Channel vs Long Channel)

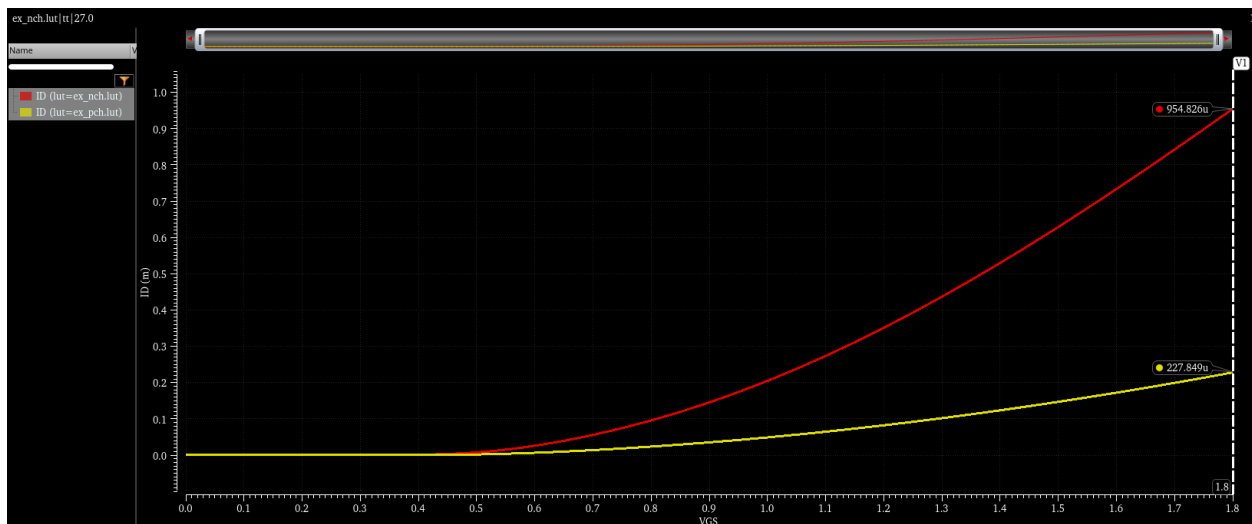




## NMOS vs PMOS (Short Channel)



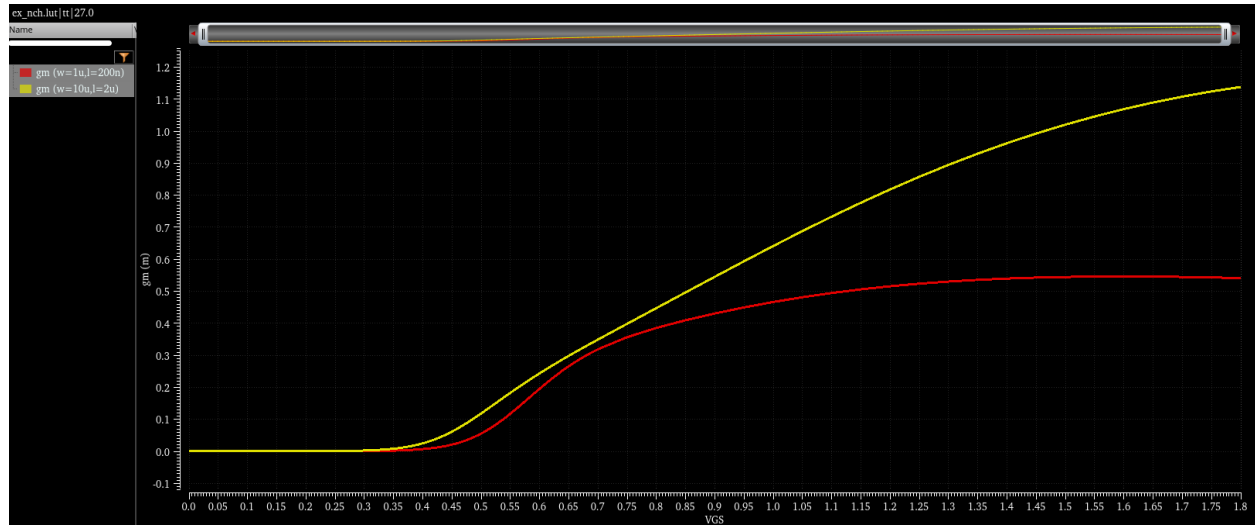
## NMOS vs PMOS (Long Channel)



## Comments on NMOS vs PMOS

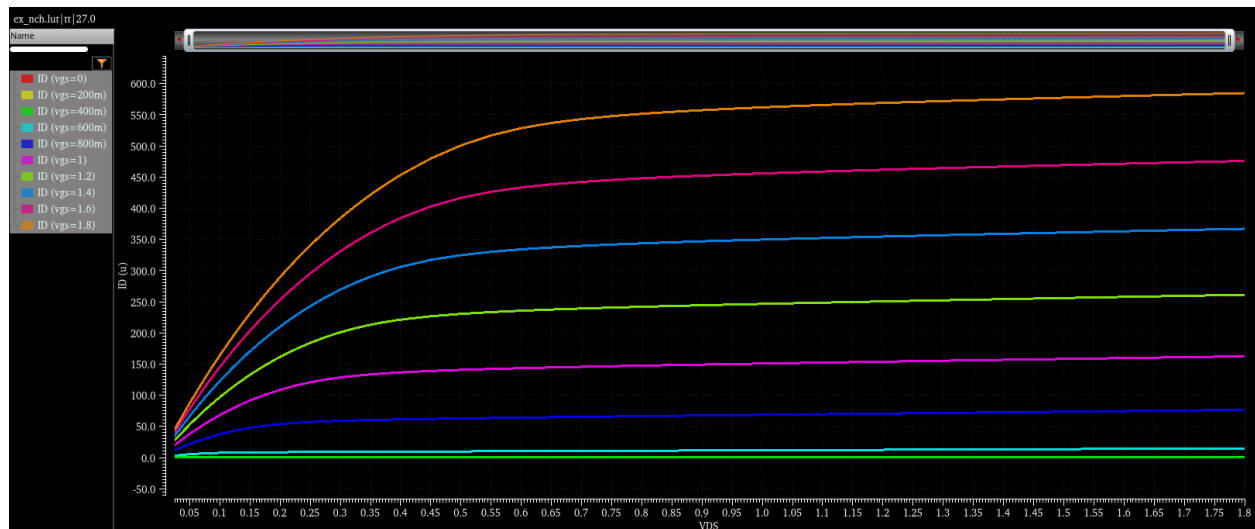
- Current ratio (NMOS/PMOS) at  $V_{GS} = V_{DD}$ :
  - Short Channel:**  $584.731/237.909 = 2.46$
  - Long Channel:**  $954.826/227.849 = 4.19$

## gm vs VGS (NMOS)

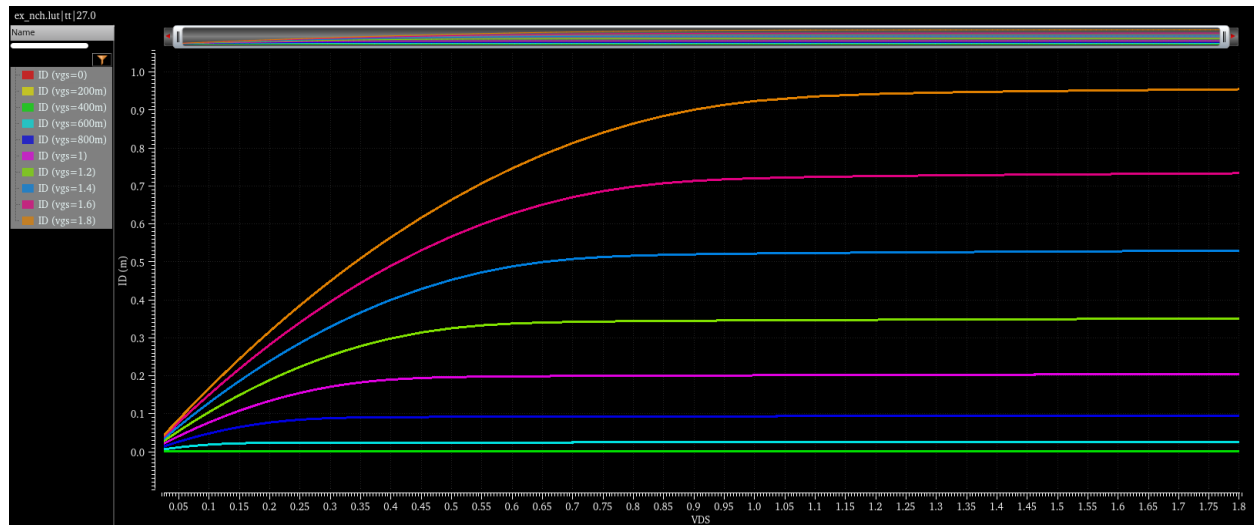


## ID vs VDS (NMOS)

### Short Channel



## Long Channel



## gm and ro in Triode and Saturation (NMOS)

